

Abstract

A second strip conductor 7 is provided such that its position in the lamination direction of the multilayer substrate 5 is different from that of the first strip conductor 8. A first grounding conductor 2 and a second grounding conductor 6 are disposed sequentially in the lamination direction of the multilayer substrate 5 and sandwiching the first strip conductor 8 and the second strip conductor 7. The first grounding conductor 2 includes a first grounding conductor portion 3 provided for the wiring prohibited area 1, and a second grounding conductor portion 4 provided for an area other than the wiring prohibited area 1. The second grounding conductor portion 4 is provided such that its position in the lamination direction of the multilayer substrate 5 is different from that of the first grounding conductor portion 3.